

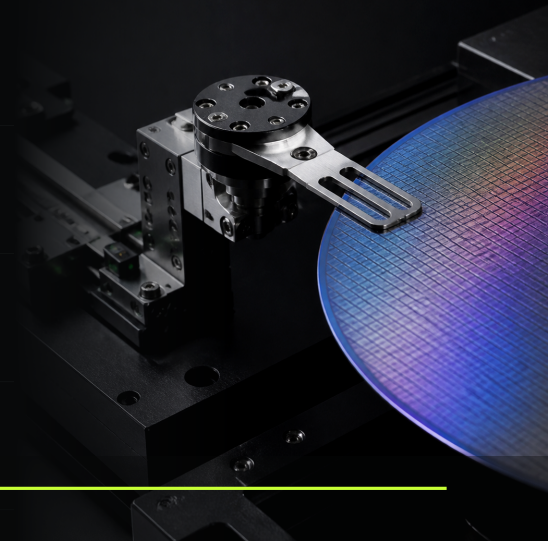
SEMICONDUCTOR EQUIPMENT

PRECISION. BUILT INTO EVERY MODULE.

Precision manufacturing and electromechanical assemblies for semiconductor equipment - build-to-print, one responsibility.

FROM PRECISION PARTS TO COMPLETE ASSEMBLIES.

Mechanics + purchased parts + wiring + assembly



01

**CNC
MILLING**

02

**CNC
TURNING**

03

**WIRE
EDM**

04

**ELECTROMECHANICAL
ASSEMBLY**

05

BUILD-TO-PRINT

BUILD-TO-PRINT PROCESS

